SN54ABT16470 ... WD PACKAGE

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- Members of the Texas Instruments *Widebus*™ Family
- State-of-the-Art *EPIC-*II*B*[™] BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16470 are 16-bit registered transceivers that contain two sets of D-type flip-flops for temporary storage of data flowing in either direction. The 'ABT16470 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate clock (CLKAB or CLKBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

To avoid false clocking of the flip-flops, clock enable (\overline{CLKEN}) should not be switched from high to low while CLK is high.

	DGG OR DL PACKAGE
(то	P VIEW)
	U
	56 10EBA
1CLKAB 2	55 1CLKBA
1CLKENAB	54 1 1CLKENBA
GND 4	53 GND
1A1 5	52 1B1
1A2 6	51 🛛 1B2
V _{CC} 7	50 🛛 V _{CC}
1A3 🛛 8	49 🛛 1B3
1A4 🛛 9	48 1B4
1A5 🛛 10	47 🛛 1B5
GND 🛛 11	46 GND
1A6 🛛 12	45 🛛 1B6
1A7 🛛 13	44 🛛 1B7
1A8 🛛 14	43 🛛 1B8
2A1 🛽 15	42 🛛 2B1
2A2 🛽 16	41 🛛 2B2
2A3 🛛 17	40 🛛 2B3
GND 🛛 18	39 🛛 GND
2A4 🛽 19	38 🛛 2B4
2A5 🛛 20	37 🛛 2B5
2A6 🛛 21	36 🛛 2B6
V _{CC} 22	35 🛛 V _{CC}
2A7 23	H
2A8 🛛 24	33 🛛 2B8
GND 🛛 25	32 🛛 GND
2CLKENAB	31 2CLKENBA
2CLKAB [27	30 🛛 2CLKBA
2 <mark>0EAB</mark> [28	29 20EBA

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16470 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT16470 is characterized for operation from -40° C to 85° C.



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SN54ABT16470, SN74ABT16470 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS085E – FEBRUARY 1991 – REVISED MAY 1997

FUNCTION TABLE[†]

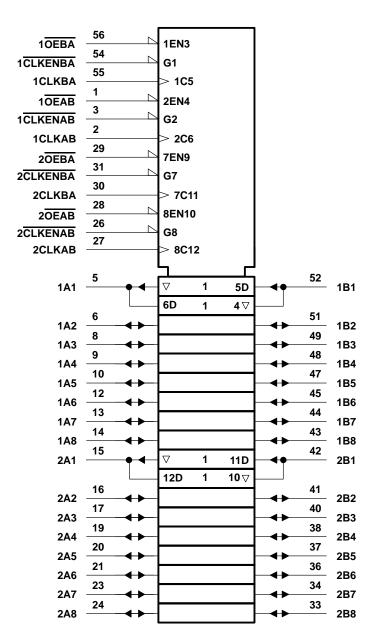
-				
	OUTPUT			
CLKENAB	CLKAB	OEAB	Α	В
н	Х	Х	Х	Z
Х	Х	Н	х	Z
L	L	L	Х	в ₀ ‡
L	\uparrow	L	L	L
L	\uparrow	L	Н	н

[†] A-to-B data flow is shown: B-to-A flow is similar but uses CLKENBA, CLKBA, and OEBA.

[‡]Output level before the indicated steady-state input conditions were established



logic symbol[†]

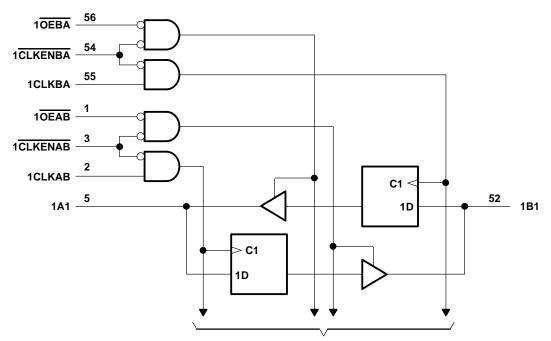


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

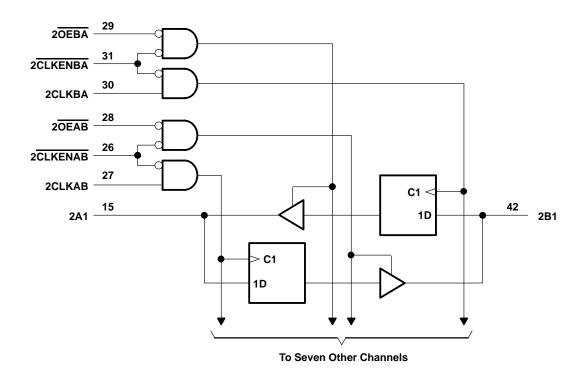


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logic diagram (positive logic)



To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (except I/O ports) (see Note 1) Voltage range applied to any output in the high or power-off state, V _O Current into any output in the low state, I _O : SN54ABT16470 SN74ABT16470	0.5 V to 7 V 0.5 V to 5.5 V 96 mA
Input clamp current, I_{IK} (V _I < 0)	
Output clamp current, I_{OK} (V _O < 0)	
Package thermal impedance, θ_{JA} (see Note 2): DGG package	
DL package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

				16470	SN74ABT16470		UNIT
			MIN	MAX	MIN	MAX	
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	EW	2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		00	^C ∨ _{CC}	0	VCC	V
ЮН	High-level output current		رد <i>ک</i>	-24		-32	mA
IOL	IOL Low-level output current		201	48		64	mA
$\Delta t / \Delta v$	Input transition rise or fall rate	Outputs enabled	N.	10		10	ns/V
Т _А	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



SCBS085E – FEBRUARY 1991 – REVISED MAY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A = 25°C			SN54AB	Г16470	SN74ABT16470			
				ΜΙΝ ΤΥΡ [†] ΜΑΧ		MIN	MAX	MIN	MAX	UNIT		
VIK		V _{CC} = 4.5 V,	lj = –18 mA			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5		v	
		V _{CC} = 5 V,	I _{OH} = –3 mA	3			3		3			
VOH			I _{OH} = -24 mA	2			2					
		V _{CC} = 4.5 V	I _{OH} = -32 mA	2*					2			
Vai			I _{OL} = 48 mA			0.55		0.55			v	
VOL		V _{CC} = 4.5 V	IOL = 64 mA			0.55*		~		0.55	V	
V _{hys}					100			E			mV	
1.	Control inputs					±1		±1		±1	uΑ	
łı	A or B ports	V _{CC} = 5.5 V,	$V_I = V_{CC}$ or GND			±100	4	±100		±100		
IOZH [‡]	ŧ	V _{CC} = 5.5 V,	V _O = 2.7 V			50	10,	50		50	μΑ	
IOZL [‡]		V _{CC} = 5.5 V,	$V_{O} = 0.5 V$			-50	^a c	-50		-50	μΑ	
loff		$V_{CC} = 0,$	V_I or $V_O \leq 4.5~V$			±100	40			±100	μA	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μA	
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-200	-50	-200	-50	-200	mA	
		V _{CC} = 5.5 V,	Outputs high			2		2		2		
ICC	A or B ports $I_O = 0$, $V_I = V_{CC}$ or GND	Outputs low			35		35		35	-		
		Outputs disabled			2		2		2			
∆ICC	T	$V_{CC} = 5.5 V$, One in Other inputs at V_{CC}				0.5		0.5		0.5	mA	
Ci	Control inputs	VI = 2.5 V or 0.5 V			3						pF	
Cio	A or B ports	V _O = 2.5 V or 0.5 V			8.5						pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 V$.

[‡] The parameters IOZH and IOZL include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V _{CC} =	$\begin{array}{c c} V_{CC} = 5 V, \\ T_A = 25^{\circ}C \end{array}$		SN54ABT16470		SN74ABT16470	
		MIN			MAX	MIN	MAX	
fclock	Clock frequency	0	150	0	150	0	150	MHz
tw#	Pulse duration, CLKAB or CLKBA high or low	3.3		3.3		3.3		ns
t _{su}	Setup time, data before CLKAB \uparrow or CLKBA \uparrow	4		4		4		ns
t _h	Hold time, data after CLKAB \uparrow or CLKBA \uparrow	1		×1		1		ns

[#]This parameter is characterized, but not production tested.



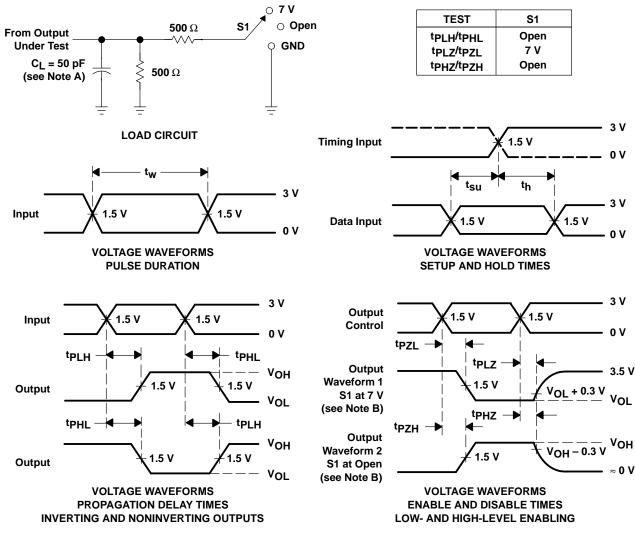
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM TO (INPUT) (OUTPUT) -		V _{CC} = 5 V, T _A = 25°C		SN54ABT16470		SN74ABT16470		UNIT	
		(001-01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			150			150		150		MHz
^t PLH	CLK	A or B	1.4	3.1	4.8	1.4	5.1	1.4	4.9	20
^t PHL	CLK	AUB	1.3	3.2	4.6	1.3	5.1	1.3	4.9	ns
^t PZH	ŌĒ	A or B	1	3.1	4.3	1	5	1	4.9	ns
^t PZL		AOIB	1.2	3.6	5.8	1.2	6.9	1.2	6.8	115
^t PHZ	OE	A or B	1.9	3.7	4.9	1.9	6	1.9	5.5	ns
^t PLZ	ÛE	AUB	1.6	3.3	4.8	1.6	5.4	1.6	5.3	115
^t PZH		A or B	1	3.4	4.6	1 4	5.8	1	5.7	20
^t PZL	CLKEN	AUB	1.2	3.9	6	1.2	7.3	1.2	7.2	ns
^t PHZ	CLKEN	A or B	1.7	3.9	5.2	1.7	6.2	1.7	5.8	200
^t PLZ	ULKEN	AUB	1.5	3.6	5.3	1.5	5.5	1.5	5.4	ns



SCBS085E - FEBRUARY 1991 - REVISED MAY 1997



PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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